Switch-mode Schottky Power Rectifier

250 V, 40 A

MBR40250G, MBR40250TG, MBRF40250TG, MBRB40250TG

Features

- 250 V Blocking Voltage
- Low Forward Voltage Drop, $V_F = 0.86$ V
- Soft Recovery Characteristic, $T_{RR} < 35$ ns
- Stable Switching Performance Over Temperature
- These Devices are Pb−Free and are RoHS Compliant

Benefits

- Reduces or Eliminates Reverse Recovery Oscillations
- Minimizes Need for EMI Filtering
- Reduces Switching Losses
- Improved Efficiency

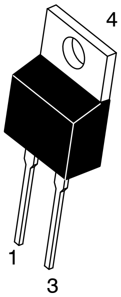
Applications

- Power Supply
- Power Management
- Automotive
- Instrumentation

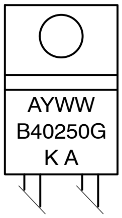
Mechanical Characteristics

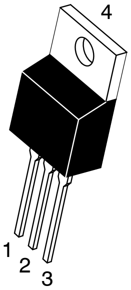
- Case: Epoxy, Molded
- Weight: 1.9 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:
  260°C Max. for 10 Seconds
- Epoxy Meets UL 94 V−0 at 0.125 in

MARKING DIAGRAMS

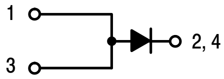


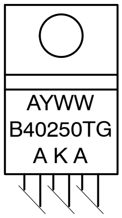
**TO−220 (2−LEAD)
CASE 221B**

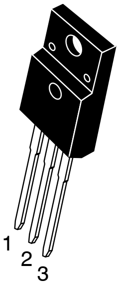




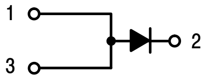
**TO−220
CASE 221A
T SUFFIX**

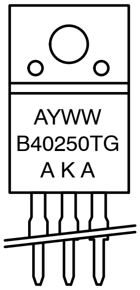


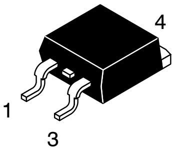




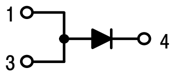
**TO−220 FULLPACK™
CASE 221D
T SUFFIX**

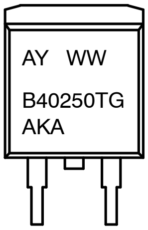






**D^2PAK 3
CASE 418B**





B40250 = Device Code
T = 3 pins
A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package
KA, AKA = Polarity Designator

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	250	V
Average Rectified Forward Current (Rated V_R) T_C = 82°C MBR40250, MBR40250T, MBRB40250T (Rated V_R) T_C = 46°C MBRF40250T	$I_{F(AV)}$	40	A
Peak Repetitive Forward Current (Rated V_R, Square Wave, 20 kHz) T_C = 82°C MBR40250, MBR40250T, MBRB40250T (Rated V_R, Square Wave, 20 kHz) T_C = 46°C MBRF40250T	I_{FRM}	80	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I_{FSM}	150	A
Storage Temperature	T_{stg}	− 65 to +175	°C
Operating Junction Temperature	T_J	− 65 to +150	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance			°C/W
Junction−to−Case	$R_{\theta JC}$		
MBR40250(T) and MBRB40250T		2.0	
MBRF40250		3.0	
Junction−to−Ambient	$R_{\theta JA}$		
MBR40250(T)		60	
MBRF40250		50	
MBRB40250T		50	

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1)	V_F		V
I_F = 20 A, T_C = 25°C		0.86	
I_F = 20 A, T_C = 125°C		0.71	
I_F = 40 A, T_C = 25°C		0.97	
I_F = 40 A, T_C = 125°C		0.86	
Maximum Instantaneous Reverse Current (Note 1)	I_R		mA
Rated DC Voltage, T_C = 25°C		0.25	
Rated DC Voltage, T_C = 125°C		30	
Maximum Reverse Recovery Time	t_{rr}		ns
I_F = 1.0 A, di/dt = 50 A/μs, T_C = 25°C		35	

DYNAMIC CHARACTERISTICS

Capacitance	C_T		pF
V_R = −5.0 V, T_C = 25°C, Frequency = 1.0 MHz		500	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

TYPICAL CHARACTERISTICS

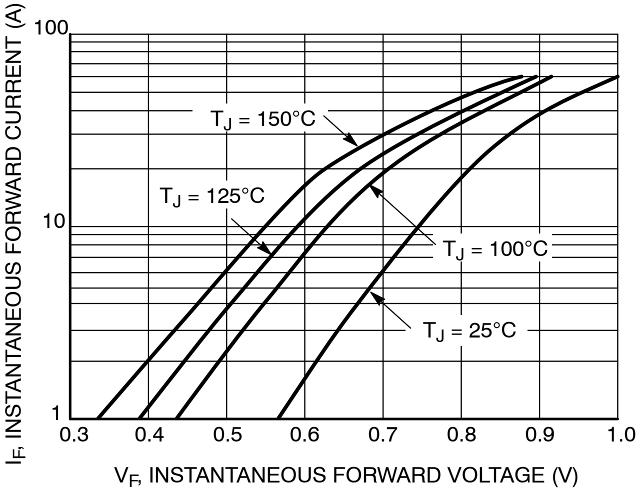


Figure 1. Typical Forward Voltage

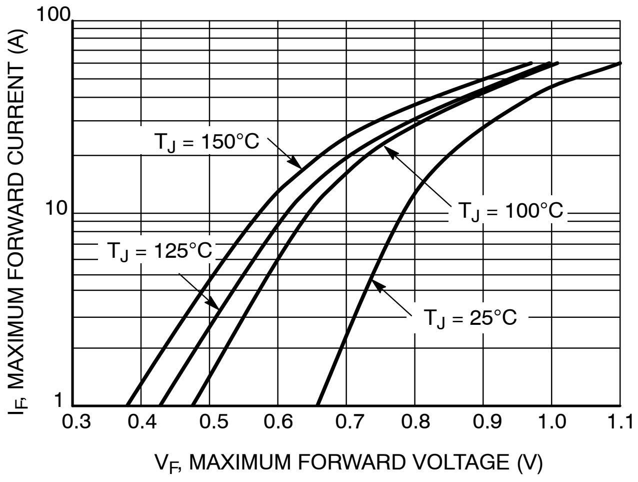


Figure 2. Maximum Forward Voltage

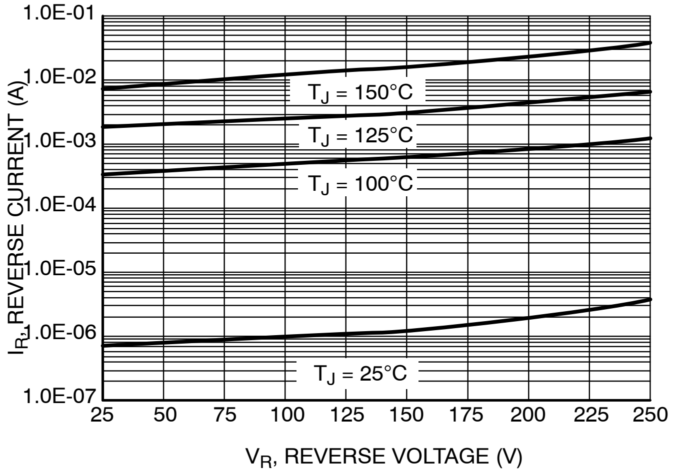


Figure 3. Typical Reverse Current

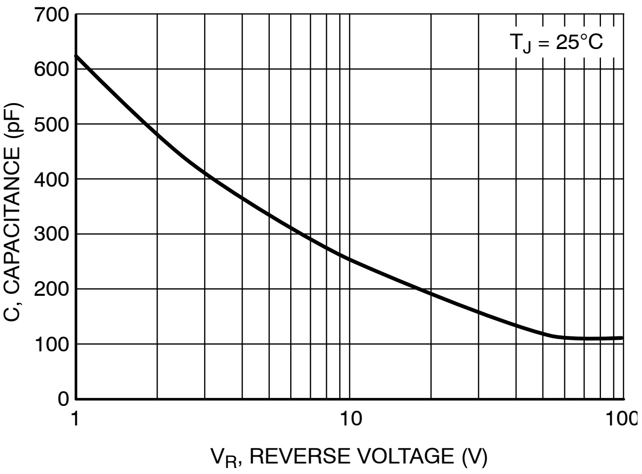


Figure 4. Typical Capacitance

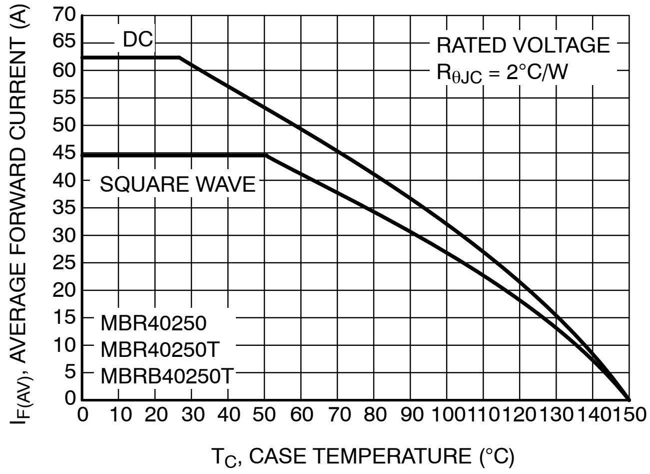


Figure 5. Current Derating (Case) for MBR40250, MBR40250T and MBRB40250T

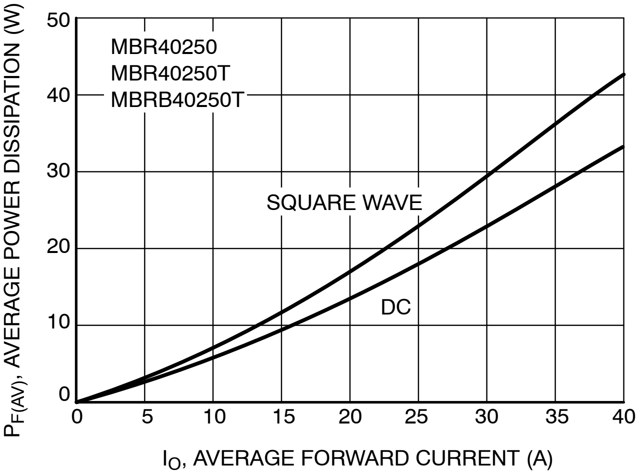


Figure 6. Forward Power Dissipation for MBR40250, MBR40250T and MBRB40250T

TYPICAL CHARACTERISTICS

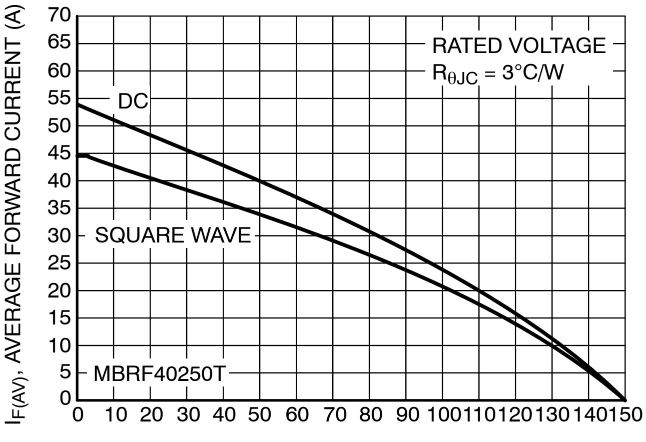


Figure 7. Current Derating (Case) for MBRF40250T

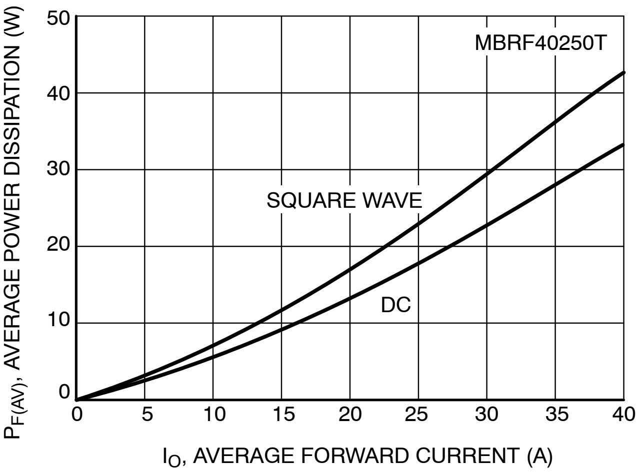


Figure 8. Forward Power Dissipation for MBRF40250T

ORDERING INFORMATION

Device	Package	Shipping†
MBR40250G	TO−220 (2−LEAD) (Pb−Free)	50 Units / Rail
MBR40250TG	TO−220 (Pb−Free)	50 Units / Rail
MBRF40250TG	TO−220 FULLPACK (Pb−Free)	50 Units / Rail
MBRB40250TG	D^2PAK 3 (Pb−Free)	50 Units / Rail
MBRB40250TT4G	D^2PAK 3 (Pb−Free)	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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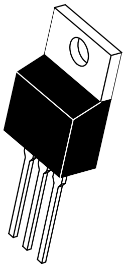
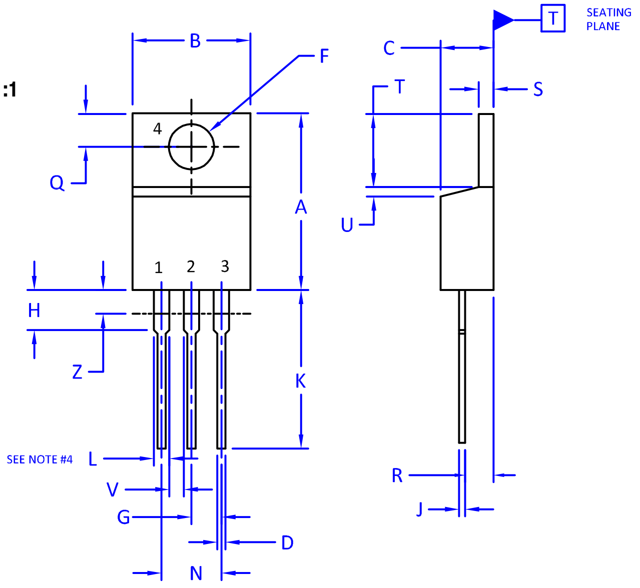
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

TO−220
CASE 221A
ISSUE AK

DATE 13 JAN 2022



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
2. CONTROLLING DIMENSION: INCHES
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.
4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
A	0.570	0.620	14.48	15.75
B	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	----	1.15	---
Z	----	0.080	---	2.04

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR
4. EMITTER

STYLE 3:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 4:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2

STYLE 5:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 6:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 8:
PIN 1. CATHODE
2. ANODE
3. EXTERNAL TRIP/DELAY
4. ANODE

STYLE 9:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 10:
PIN 1. GATE
2. SOURCE
3. DRAIN
4. SOURCE

STYLE 11:
PIN 1. DRAIN
2. SOURCE
3. GATE
4. SOURCE

STYLE 12:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. NOT CONNECTED

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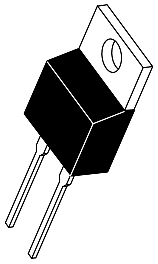
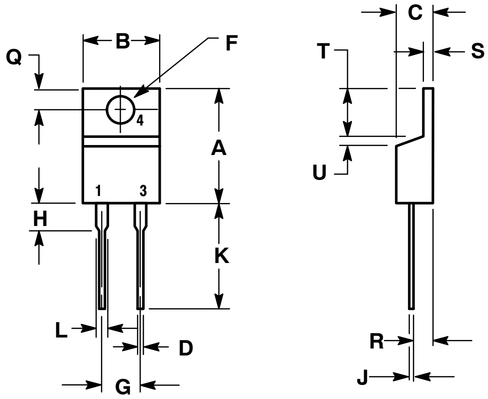
DESCRIPTION:	**TO−220**	**PAGE 1 OF 1**



SCALE 1:1

TO−220, 2−LEAD
CASE 221B−04
ISSUE F

DATE 12 APR 2013



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.039	0.64	1.00
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

STYLE 1:
PIN 1. CATHODE
2. N/A
3. ANODE
4. CATHODE

STYLE 2:
PIN 1. ANODE
2. N/A
3. CATHODE
4. ANODE

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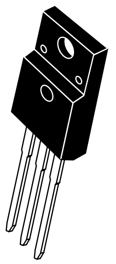
DESCRIPTION:	**TO−220, 2−LEAD**	**PAGE 1 OF 1**

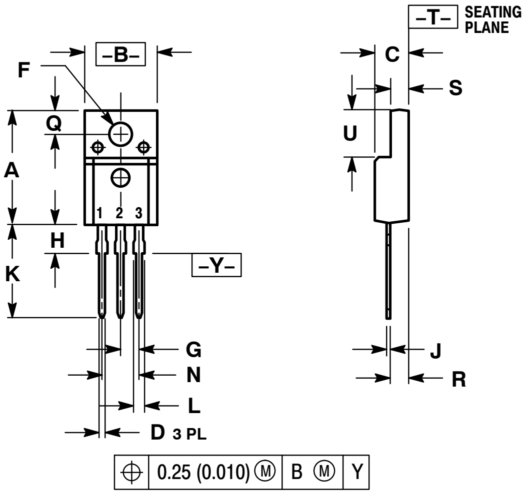
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

TO−220 FULLPAK
CASE 221D−03
ISSUE K

DATE 27 FEB 2009



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D−01 THRU 221D−02 OBSOLETE, NEW STANDARD 221D−03.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

STYLE 1:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 2:
PIN 1. BASE
2. COLLECTOR
3. EMITTER

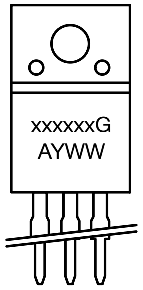
STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE

STYLE 4:
PIN 1. CATHODE
2. ANODE
3. CATHODE

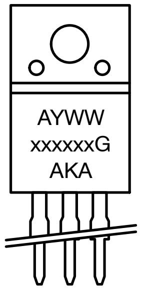
STYLE 5:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 6:
PIN 1. MT 1
2. MT 2
3. GATE

MARKING DIAGRAMS



Bipolar

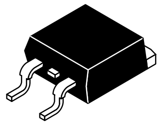


Rectifier

xxxxxx = Specific Device Code
G = Pb−Free Package
A = Assembly Location
Y = Year
WW = Work Week

A = Assembly Location
Y = Year
WW = Work Week
xxxxxx = Device Code
G = Pb−Free Package
AKA = Polarity Designator

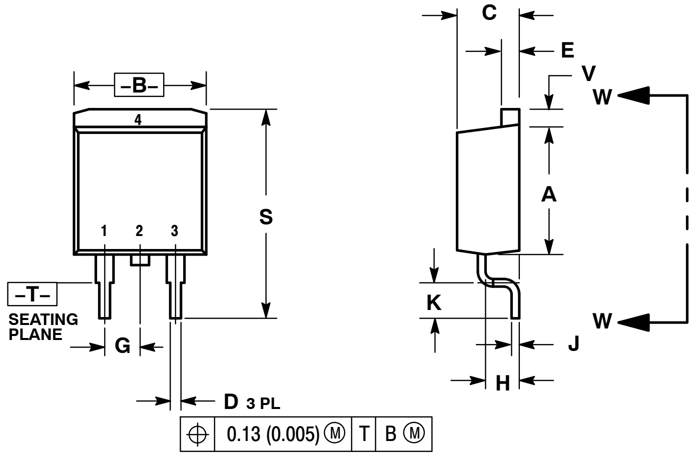
DOCUMENT NUMBER:	**98ASB42514B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**TO−220 FULLPAK**	**PAGE 1 OF 1**



SCALE 1:1

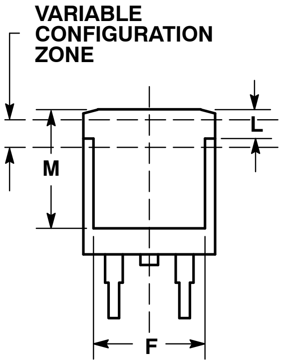
D^2PAK 3
CASE 418B−04
ISSUE L

DATE 17 FEB 2015

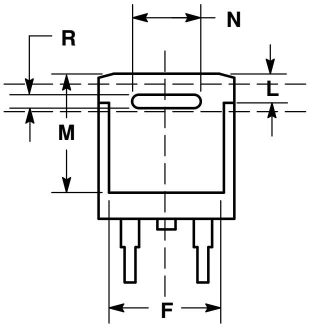


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B−01 THRU 418B−03 OBSOLETE, NEW STANDARD 418B−04.

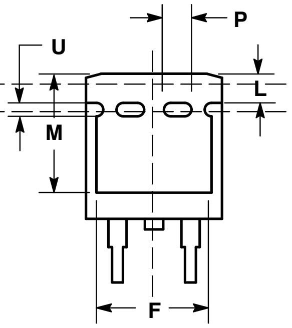
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



VIEW W−W
1



VIEW W−W
2



VIEW W−W
3

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 5:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 6:
PIN 1. NO CONNECT
2. CATHODE
3. ANODE
4. CATHODE

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

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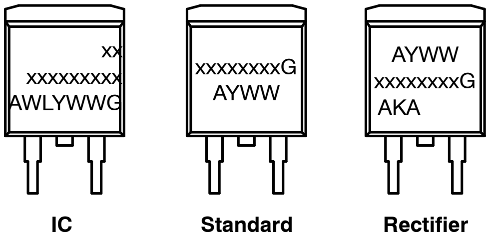
DESCRIPTION:	**D^2PAK 3**	**PAGE 1 OF 2**

D^2PAK 3

CASE 418B−04
ISSUE L

DATE 17 FEB 2015

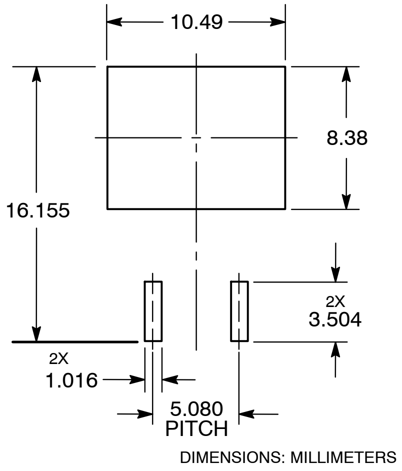
GENERIC MARKING DIAGRAM*



xx = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package
AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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